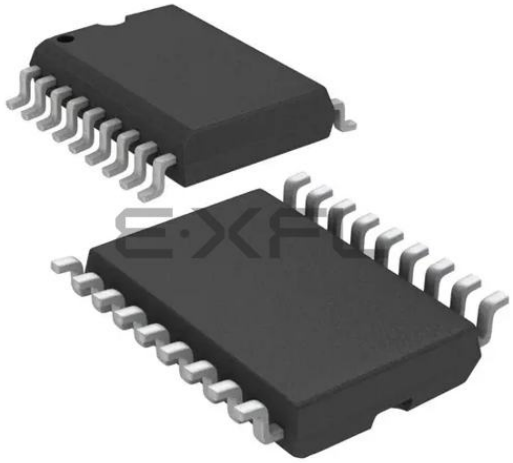
Microchip Technology - PIC16C715T-20E/SO Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c715t-20e-so

4.2.2.6 PCON REGISTER

Applicable Devices	710	71	711	715

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external $\overline{MCLR}$ Reset or WDT Reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset (BOR) condition from a Power-on Reset condition. For the PIC16C715 the PCON register also contains status bits MPEEN and PER. MPEEN reflects the value of the MPEEN bit in the configuration word. PER indicates a parity error reset has occurred.

Note: $\overline{BOR}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{BOR}$ is clear, indicating a brown-out has occurred. The $\overline{BOR}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 4-12: PCON REGISTER (ADDRESS 8Eh), PIC16C710/711

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{POR}$:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOR}$:** Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

FIGURE 4-13: PCON REGISTER (ADDRESS 8Eh), PIC16C715

R-U	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-q
MPEEN	—	—	—	—	$\overline{PER}$	$\overline{POR}$	$\overline{BOR}$(1)
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **MPEEN:** Memory Parity Error Circuitry Status bit
Reflects the value of configuration word bit, MPEEN

bit 6-3: **Unimplemented:** Read as '0'

bit 2: **$\overline{PER}$:** Memory Parity Error Reset Status bit
1 = No Error occurred
0 = Program Memory Fetch Parity Error occurred (must be set in software after a Parity Error Reset)

bit 1: **$\overline{POR}$:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOR}$:** Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

```
ORG 0x500
BSF     PCLATH,3  ;Select page 1 (800h-FFFh)
BCF     PCLATH,4  ;Only on >4K devices
CALL    SUB1_P1   ;Call subroutine in
        :         ;page 1 (800h-FFFh)
        :
        :
ORG 0x900
SUB1_P1:          ;called subroutine
        :         ;page 1 (800h-FFFh)
        :
RETURN            ;return to Call subroutine
                  ;in page 0 (000h-7FFh)
```

4.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

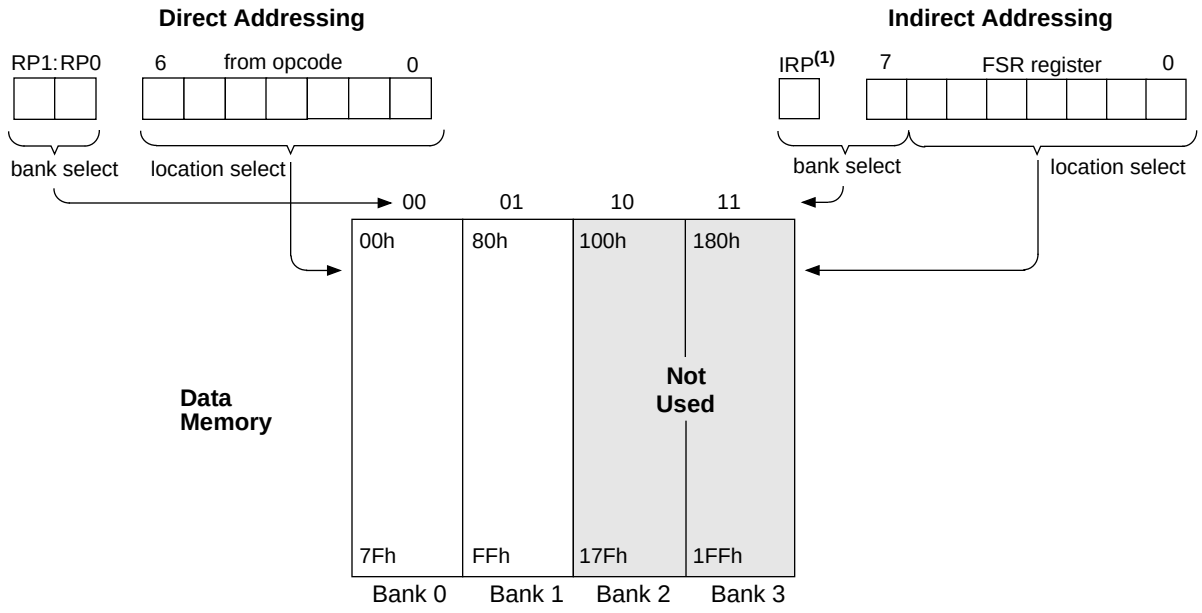
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = '0') will read 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-15. However, IRP is not used in the PIC16C71X devices.

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 4-2.

EXAMPLE 4-2: INDIRECT ADDRESSING

```
        movlw  0x20   ;initialize pointer
        movwf  FSR    ;to RAM
NEXT    clrf   INDF   ;clear INDF register
        incf   FSR,F  ;inc pointer
        btfss  FSR,4  ;all done?
        goto   NEXT   ;no clear next
CONTINUE
        :              ;yes continue
```

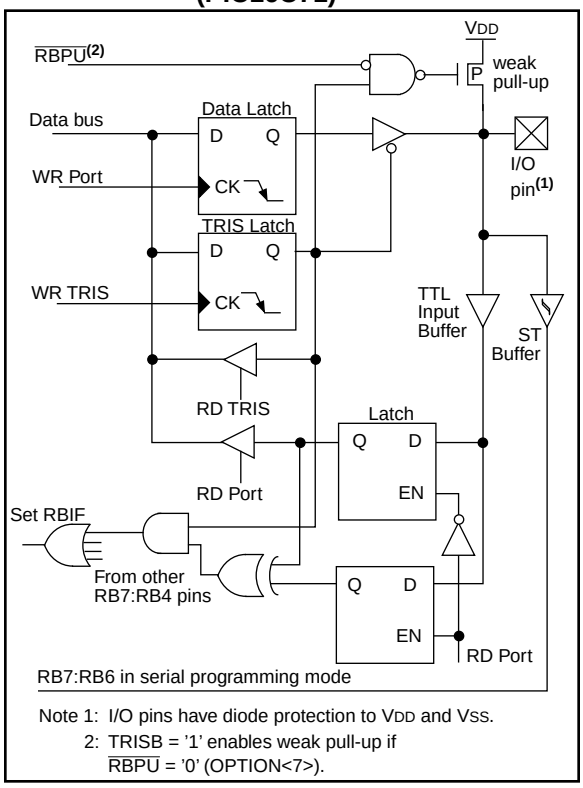
FIGURE 4-15: DIRECT/INDIRECT ADDRESSING



For register file map detail see Figure 4-4.

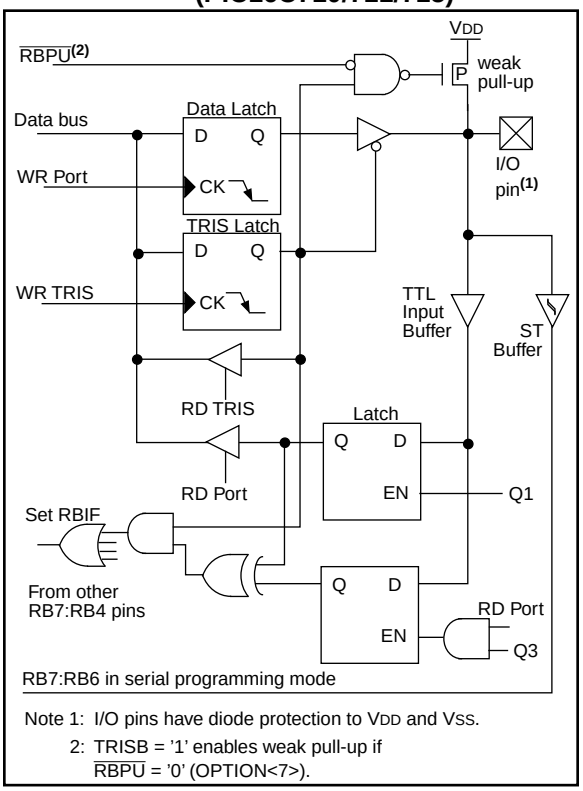
Note 1: The RP1 and IRP bits are reserved, always maintain these bits clear.

FIGURE 5-4: BLOCK DIAGRAM OF RB7:RB4 PINS (PIC16C71)



Note 1: I/O pins have diode protection to VDD and VSS.
2: TRISB = '1' enables weak pull-up if $\overline{RBPU}$ = '0' (OPTION<7>).

FIGURE 5-5: BLOCK DIAGRAM OF RB7:RB4 PINS (PIC16C710/711/715)



Note 1: I/O pins have diode protection to VDD and VSS.
2: TRISB = '1' enables weak pull-up if $\overline{RBPU}$ = '0' (OPTION<7>).

TABLE 5-3: PORTB FUNCTIONS

Name	Bit#	Buffer	Function
RB0/INT	bit0	TTL/ST(1)	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST(2)	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming clock.
RB7	bit7	TTL/ST(2)	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger input
Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.

5.3 I/O Programming Considerations

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched to an output, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-3 shows the effect of two sequential read-modify-write instructions on an I/O port.

EXAMPLE 5-3: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

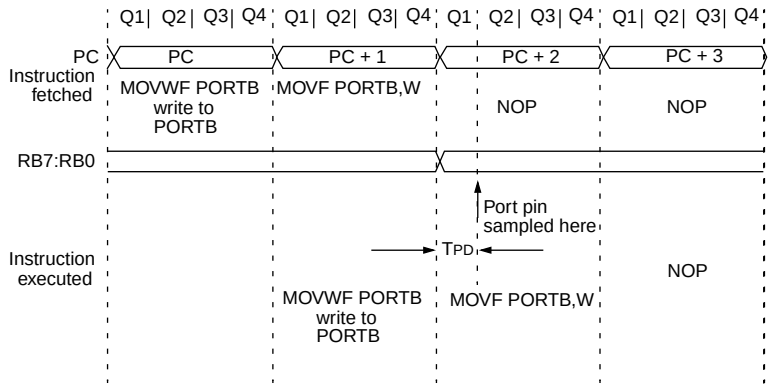
```
;Initial PORT settings: PORTB<7:4> Inputs
;                       PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
;
;                    PORT latch  PORT pins
;                    ----------  ---------
  BCF PORTB, 7      ; 01pp pppp    11pp pppp
  BCF PORTB, 6      ; 10pp pppp    11pp pppp
  BSF STATUS, RP0   ;
  BCF TRISB, 7      ; 10pp pppp    11pp pppp
  BCF TRISB, 6      ; 10pp pppp    10pp pppp
;
;Note that the user may have expected the
;pin values to be 00pp ppp. The 2nd BCF
;caused RB7 to be latched as the pin value
;(high).
```

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin (“wired-or”, “wired-and”). The resulting high output currents may damage the chip.

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-6). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

FIGURE 5-6: SUCCESSIVE I/O OPERATION



Note:

This example shows a write to PORTB followed by a read from PORTB.

Note that:

data setup time = ($0.25T_{CY} - T_{PD}$)

where T_{CY} = instruction cycle
T_{PD} = propagation delay

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

8.0 SPECIAL FEATURES OF THE CPU

Applicable Devices	710	71	711	715

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real-time applications. The PIC16CXX family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator selection
- Reset
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR) (PIC16C710/711/715)
  - Parity Error Reset (PER) (PIC16C715)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP
- Code protection
- ID locations
- In-circuit serial programming

The PIC16CXX has a Watchdog Timer which can be shut off only through configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in reset while the power supply stabilizes. With these two timers on-chip, most applications need no external reset circuitry.

SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through external reset, Watchdog Timer Wake-up, or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

8.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h - 3FFFh), which can be accessed only during programming.

FIGURE 8-1: CONFIGURATION WORD FOR PIC16C71

—	—	—	—	—	—	—	—	—	CP0	PWRTE	WDTE	FOSC1	FOSC0

bit13 bit0

Register: CONFIG
Address 2007h

bit 13-5: **Unimplemented:** Read as '1'

bit 4: **CP0:** Code protection bit
1 = Code protection off
0 = All memory is code protected, but 00h - 3Fh is writable

bit 3: **PWRTE:** Power-up Timer Enable bit
1 = Power-up Timer enabled
0 = Power-up Timer disabled

bit 2: **WDTE:** Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0:** Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

9.1 Instruction Descriptions

ADDLW **Add Literal and W**

Syntax: [*label*] ADDLW k

Operands: $0 \le k \le 255$

Operation: (W) + k → (W)

Status Affected: C, DC, Z

Encoding:

11	111x	kkkk	kkkk

Description: The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example:
```
ADDLW   0x15
```
Before Instruction
W = 0x10
After Instruction
W = 0x25

ANDLW **AND Literal with W**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. (k) → (W)

Status Affected: Z

Encoding:

11	1001	kkkk	kkkk

Description: The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal "k"	Process data	Write to W

Example
```
ANDLW   0x5F
```
Before Instruction
W = 0xA3
After Instruction
W = 0x03

ADDWF **Add W and f**

Syntax: [*label*] ADDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) + (f) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0111	dfff	ffff

Description: Add the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to Dest

Example
```
ADDWF   FSR, 0
```
Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0xD9
FSR = 0xC2

ANDWF **AND W with f**

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .AND. (f) → (dest)

Status Affected: Z

Encoding:

00	0101	dfff	ffff

Description: AND the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to Dest

Example
```
ANDWF   FSR, 1
```
Before Instruction
W = 0x17
FSR = 0xC2
After Instruction
W = 0x17
FSR = 0x02

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See Section 8.8 for more details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	NOP	NOP	Go to Sleep

Example: SLEEP

SUBLW Subtract W from Literal

Syntax: [*label*] SUBLW k

Operands: 0 ≤ k ≤ 255

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example 1: SUBLW 0x02

Before Instruction
W = 1
C = ?
Z = ?

After Instruction
W = 1
C = 1; result is positive
Z = 0

Example 2: Before Instruction
W = 2
C = ?
Z = ?

After Instruction
W = 0
C = 1; result is zero
Z = 1

Example 3: Before Instruction
W = 3
C = ?
Z = ?

After Instruction
W = 0xFF
C = 0; result is negative
Z = 0

Applicable Devices	710	71	711	715

11.1 DC Characteristics: PIC16C710-04 (Commercial, Industrial, Extended) PIC16C711-04 (Commercial, Industrial, Extended) PIC16C710-10 (Commercial, Industrial, Extended) PIC16C711-10 (Commercial, Industrial, Extended) PIC16C710-20 (Commercial, Industrial, Extended) PIC16C711-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param. No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	4.0	-	6.0	V	XT, RC and LP osc configuration
D001A			4.5	-	5.5	V	HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
			3.7	4.0	4.4	V	Extended Range Only
D010	Supply Current (Note 2)	IDD	-	2.7	5	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	13.5	30	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 5)	ΔIBOR	-	300*	500	µA	BOR enabled VDD = 5.0V
D020	Power-down Current (Note 3)	IPD	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	21	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	24	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	1.5	30	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 5)	ΔIBOR	-	300*	500	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	710	71	711	715

11.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

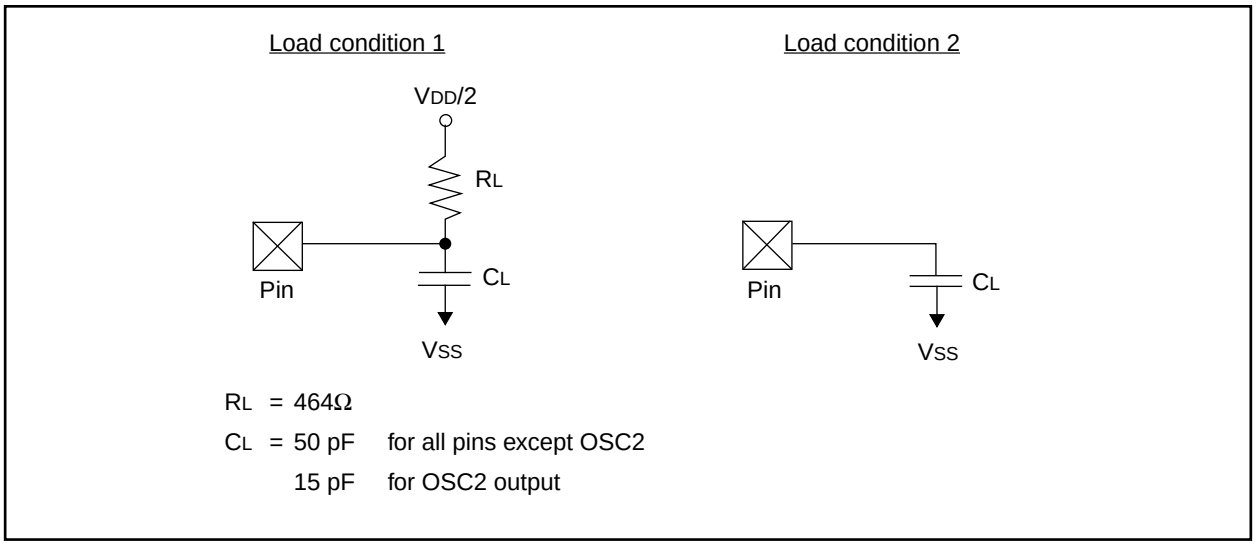
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance

FIGURE 11-1: LOAD CONDITIONS



Applicable Devices	710	71	711	715

12.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C710 AND PIC16C711

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified V_{DD} range). This is for information only and devices are guaranteed to operate properly only within the specified range.

Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at, 25°C, while 'max' or 'min' represents (mean +3σ) and (mean -3σ) respectively where σ is standard deviation.

FIGURE 12-1: TYPICAL I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)

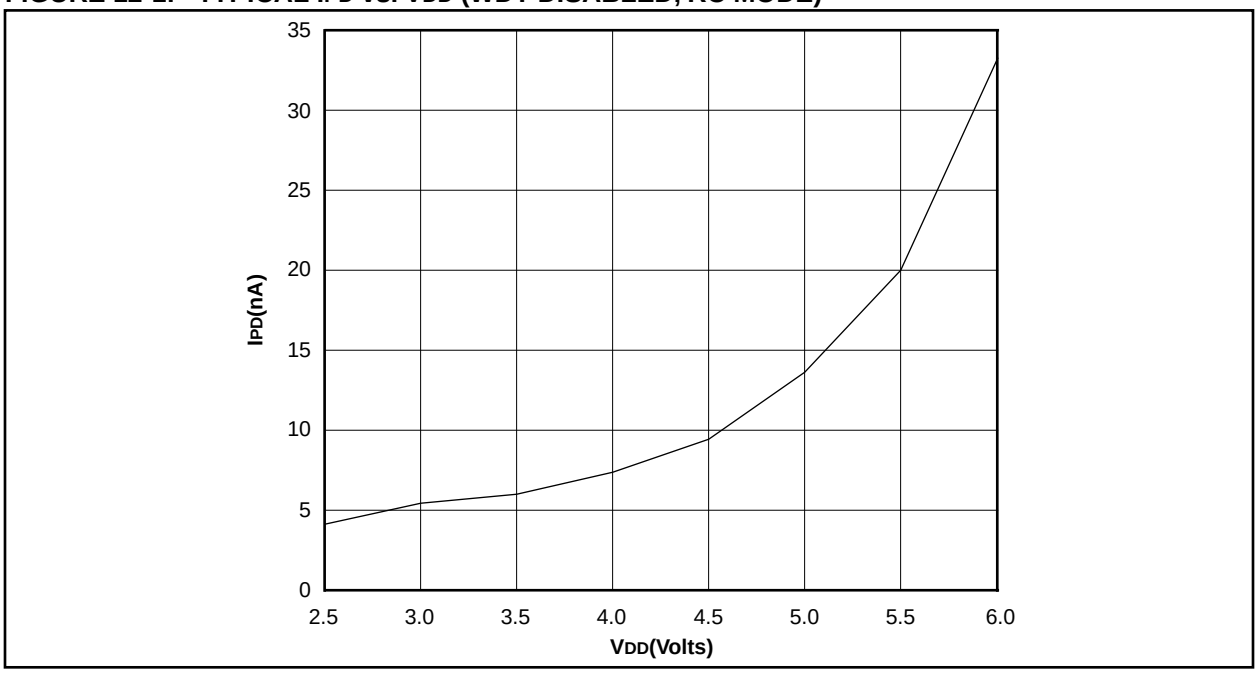
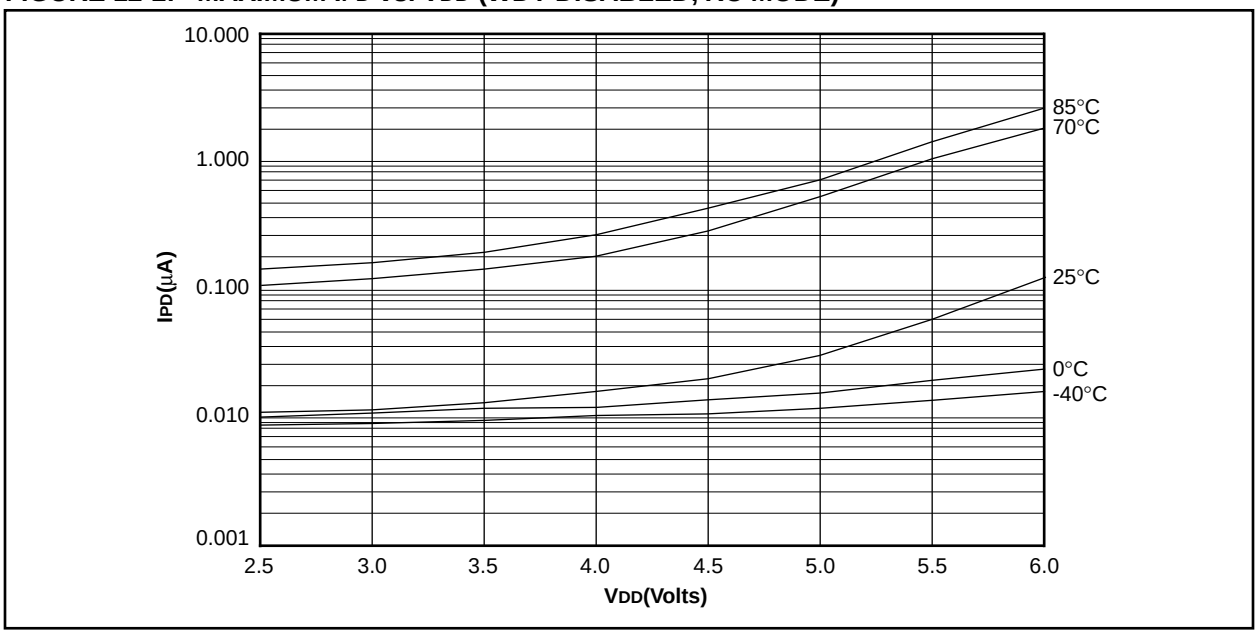


FIGURE 12-2: MAXIMUM I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)



Applicable Devices	710	71	711	715

FIGURE 12-3: TYPICAL IPD vs. VDD @ 25°C (WDT ENABLED, RC MODE)

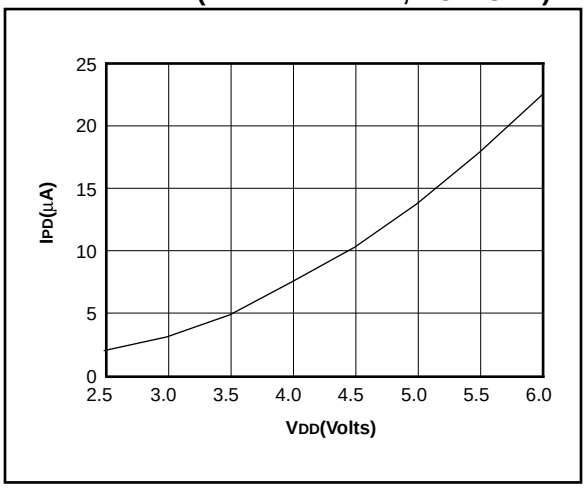


FIGURE 12-4: MAXIMUM IPD vs. VDD (WDT ENABLED, RC MODE)

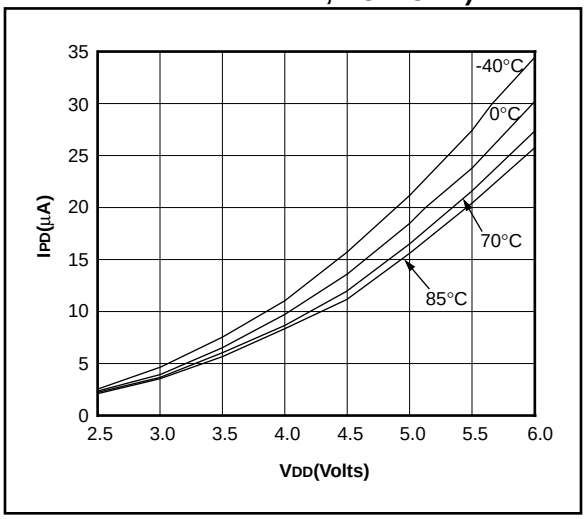
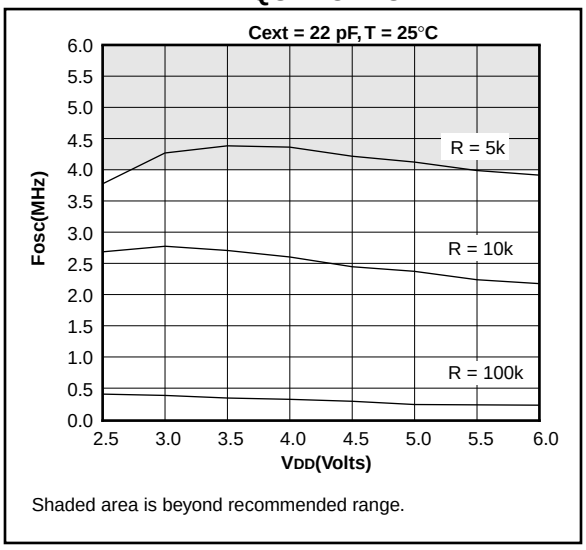


FIGURE 12-5: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD



Shaded area is beyond recommended range.

FIGURE 12-6: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

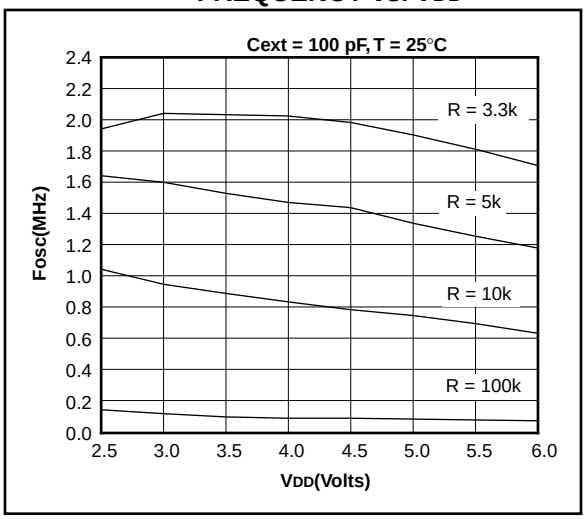
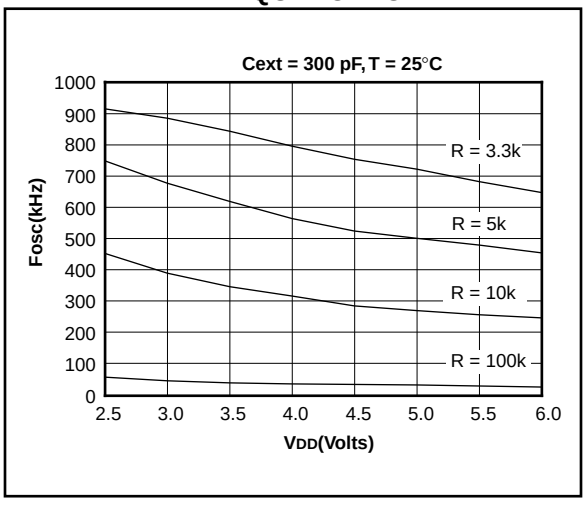


FIGURE 12-7: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD



Applicable Devices	710	71	711	715

TABLE 13-6: A/D CONVERTER CHARACTERISTICS:
PIC16C715-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C715-10 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C715-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	NR	Resolution	—	—	8-bits	—	VREF = VDD, VSS ≤ AIN ≤ VREF
	NINT	Integral error	—	—	less than ±1 LSb	—	VREF = VDD, VSS ≤ AIN ≤ VREF
	NDIF	Differential error	—	—	less than ±1 LSb	—	VREF = VDD, VSS ≤ AIN ≤ VREF
	NFS	Full scale error	—	—	less than ±1 LSb	—	VREF = VDD, VSS ≤ AIN ≤ VREF
	NOFF	Offset error	—	—	less than ±1 LSb	—	VREF = VDD, VSS ≤ AIN ≤ VREF
	—	Monotonicity	—	guaranteed	—	—	VSS ≤ AIN ≤ VREF
	VREF	Reference voltage	2.5V	—	VDD + 0.3	V	
	VAIN	Analog input voltage	VSS - 0.3	—	VREF + 0.3	V	
	ZAIN	Recommended impedance of analog voltage source	—	—	10.0	kΩ	
	IAD	A/D conversion current (VDD)	—	180	—	µA	Average current consumption when A/D is on. (Note 1)
	IREF	VREF input current (Note 2)	—	—	1 10	mA µA	During sampling All other times

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

Applicable Devices	710	71	711	715

14.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C715

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified V_{DD} range). This is for information only and devices are guaranteed to operate properly only within the specified range.

Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at, 25°C, while 'max' or 'min' represents (mean +3σ) and (mean -3σ) respectively where σ is standard deviation.

FIGURE 14-1: TYPICAL I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)

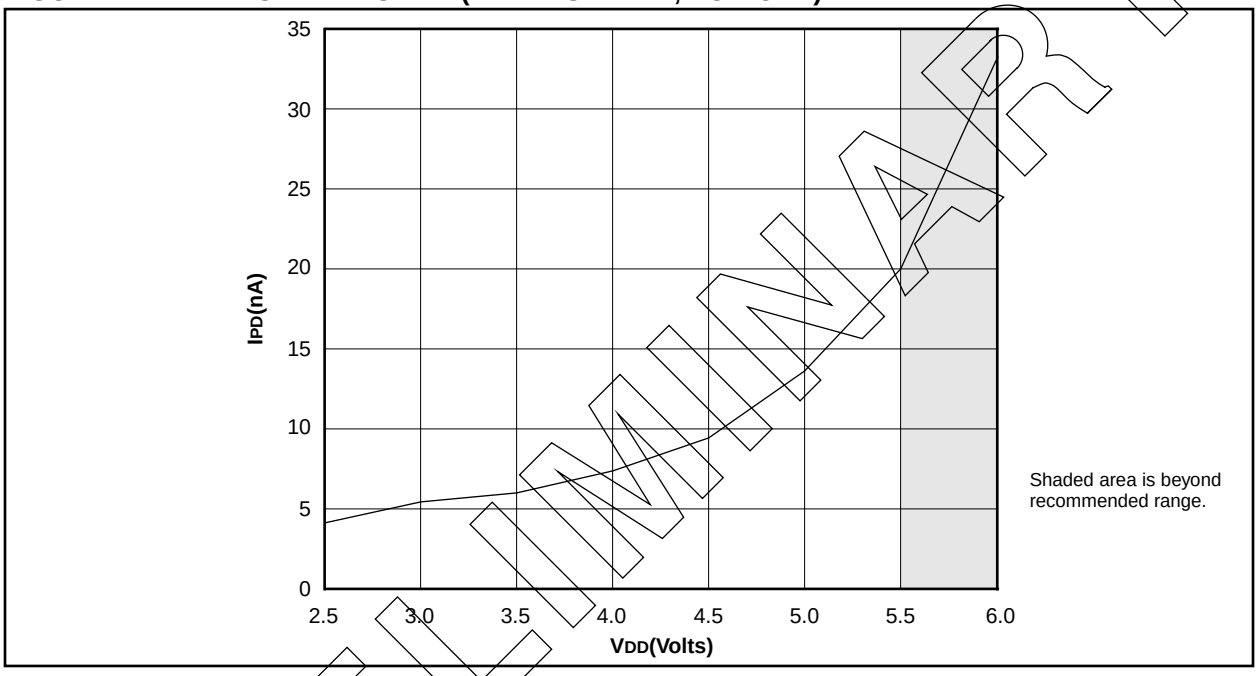
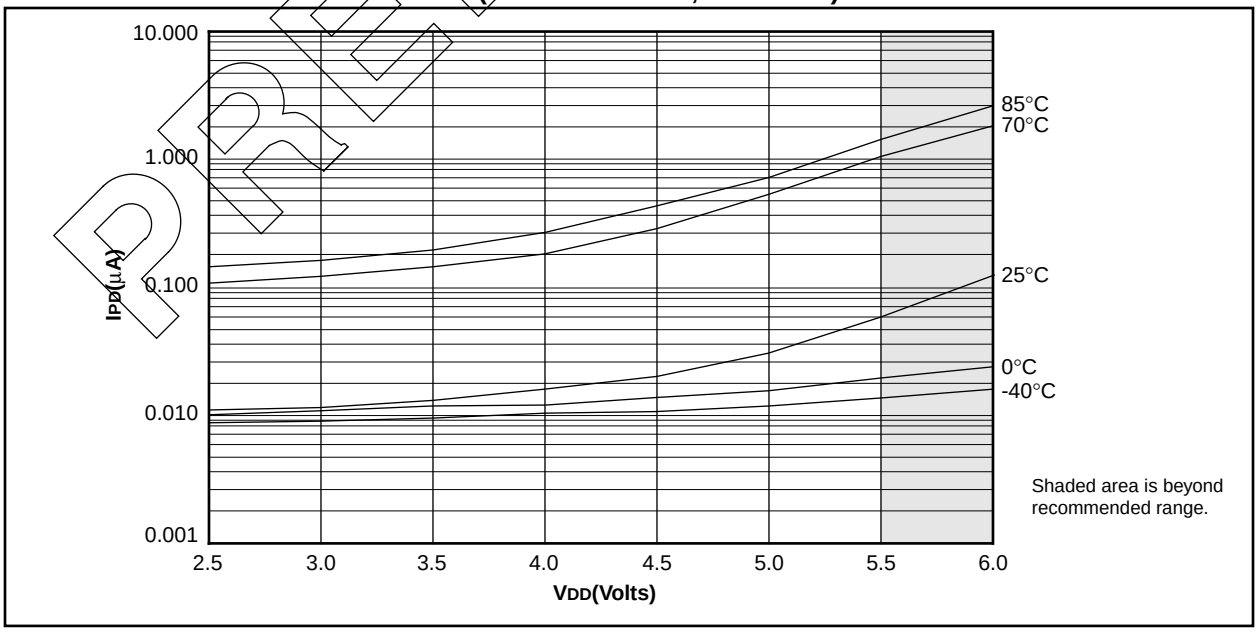


FIGURE 14-2: MAXIMUM I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)



Applicable Devices	710	71	711	715

FIGURE 14-16: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

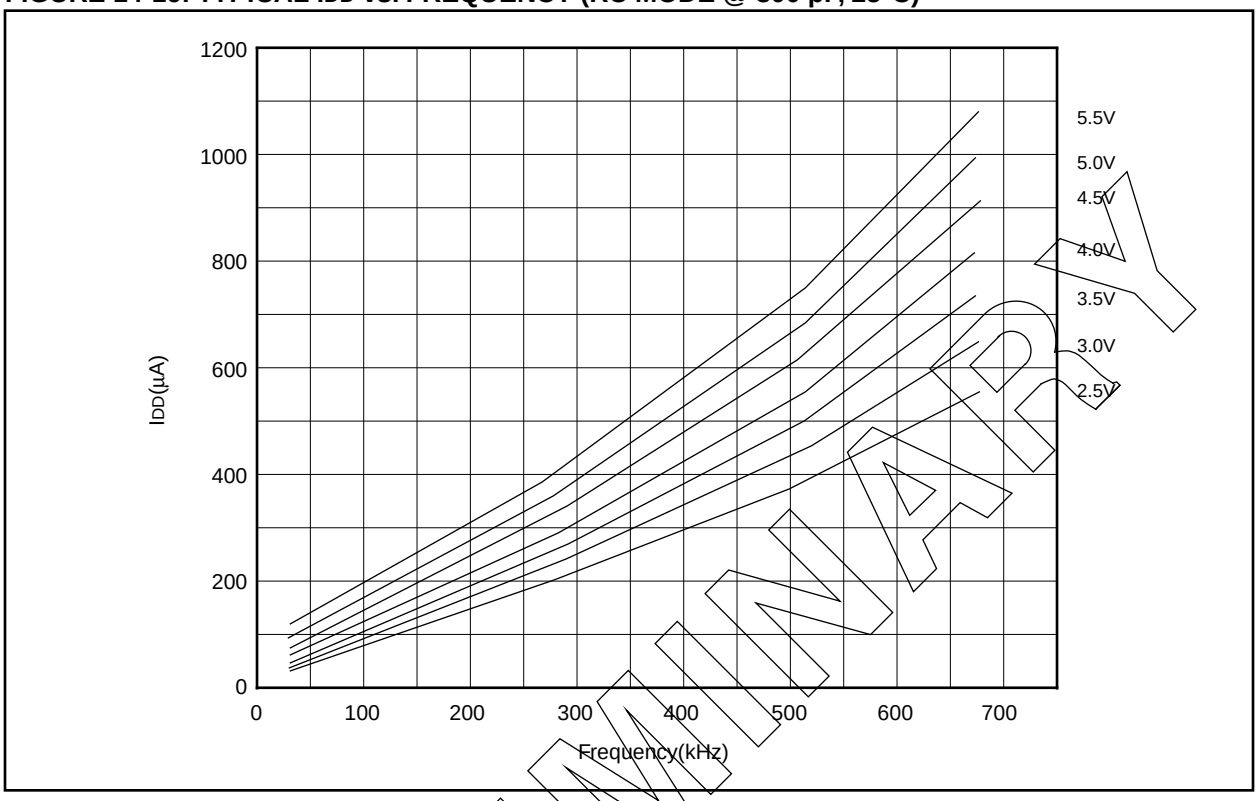
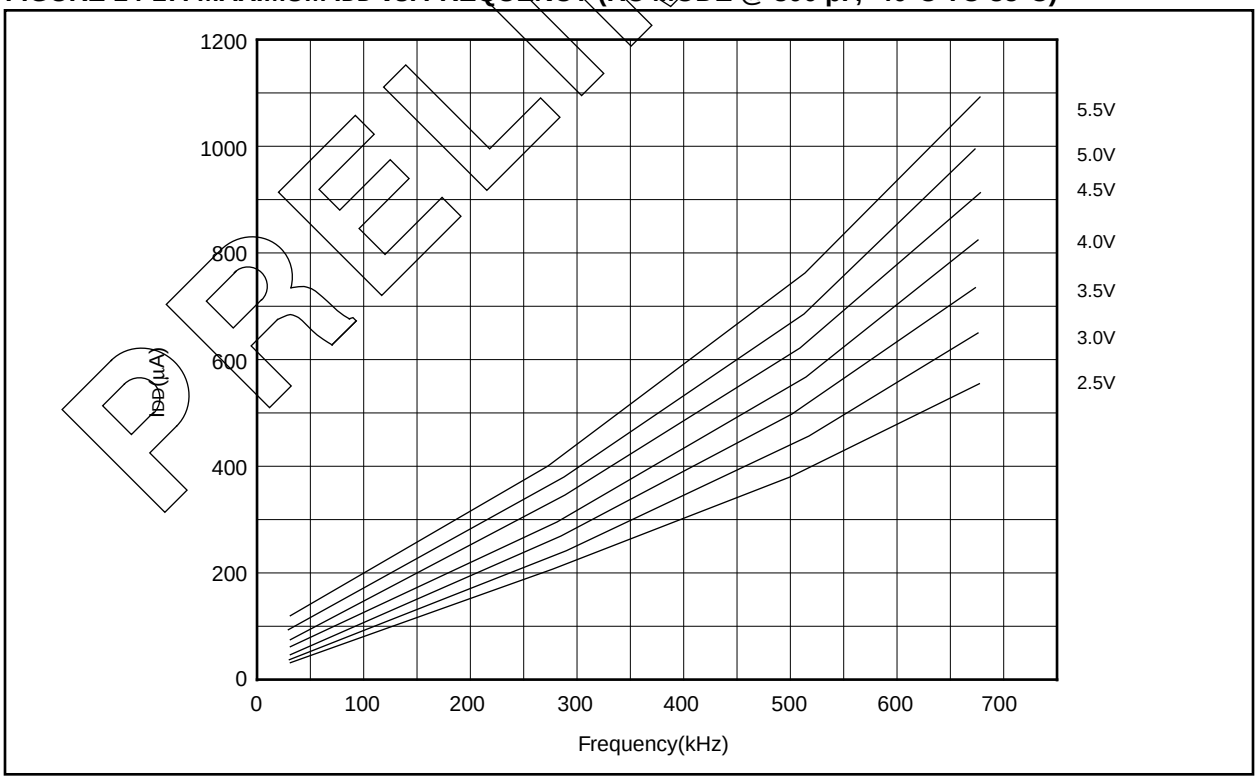


FIGURE 14-17: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Applicable Devices	710	71	711	715

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C71

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. **In some graphs or tables the data presented are outside specified operating range (e.g. outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range.**

Note:	The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution while 'max' or 'min' represents (mean + 3σ) and (mean - 3σ) respectively where σ is standard deviation.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY VS. TEMPERATURE

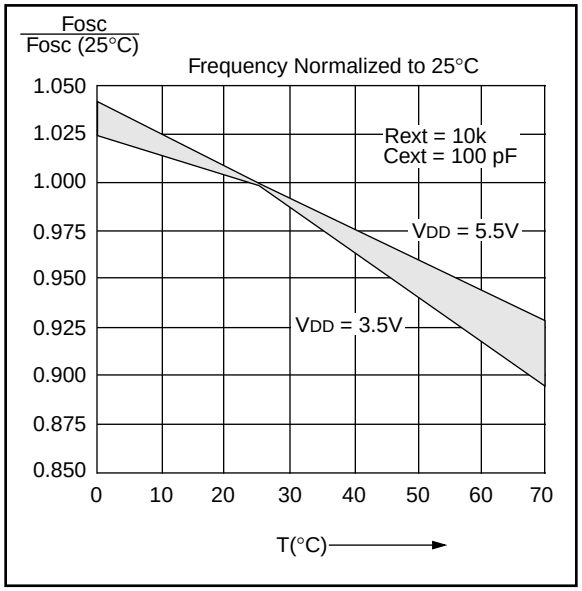


FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY VS. VDD

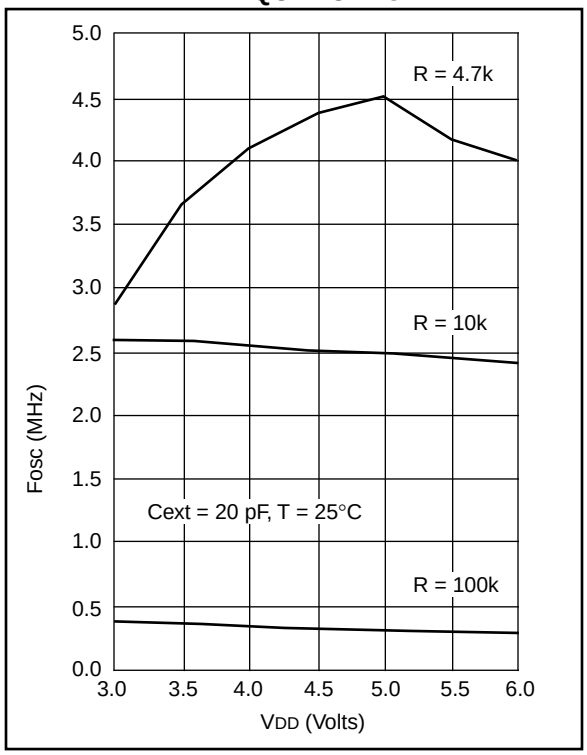
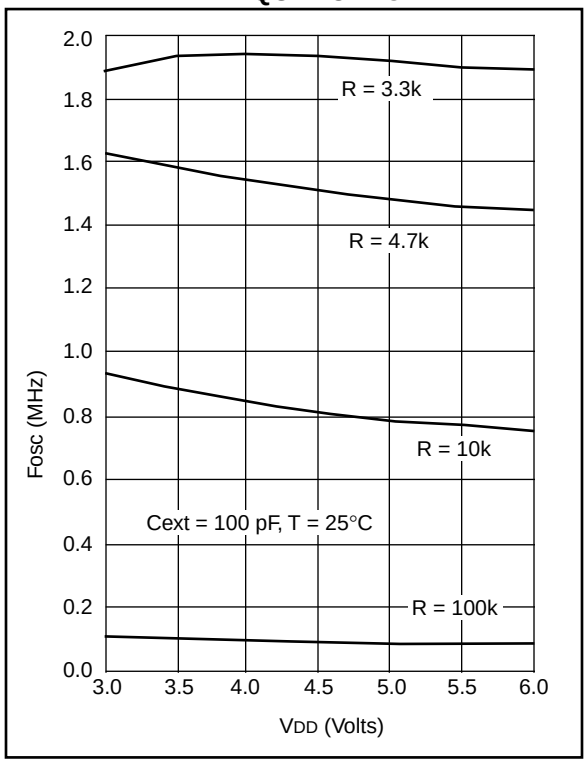


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY VS. VDD



Applicable Devices	710	71	711	715

FIGURE 16-21: IOL VS. VOL, VDD = 3V

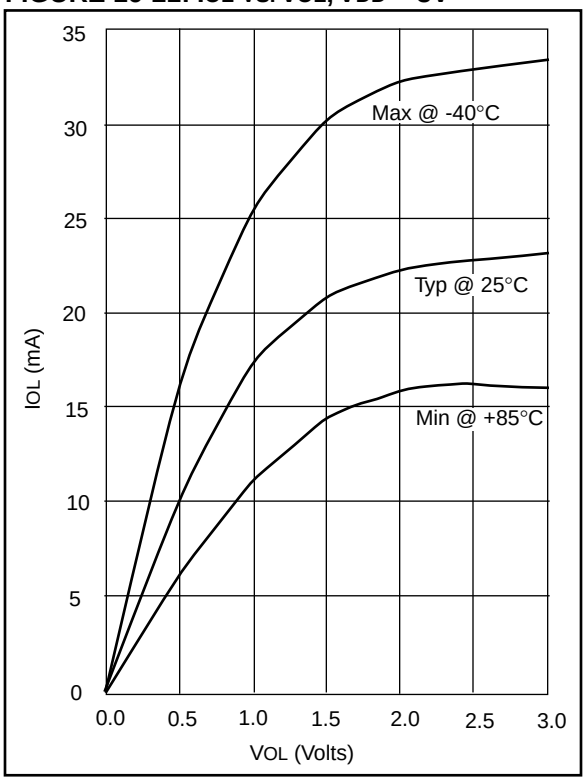
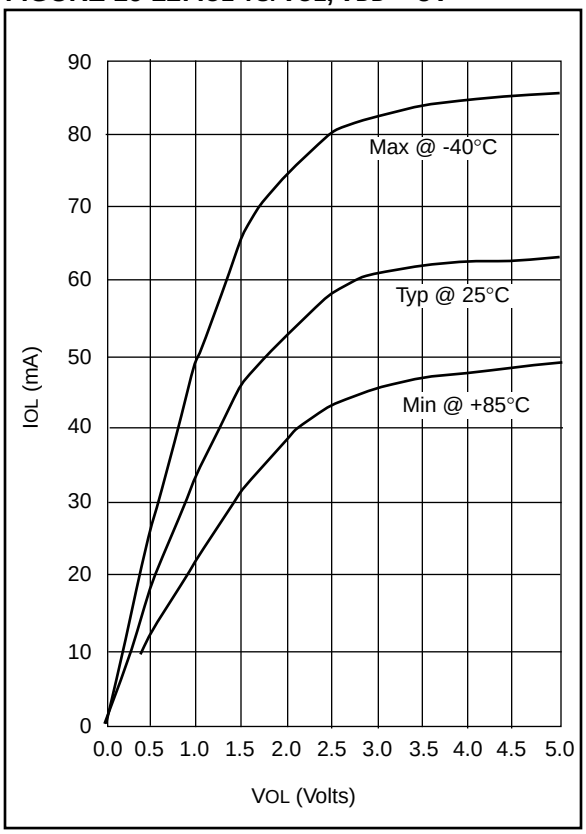
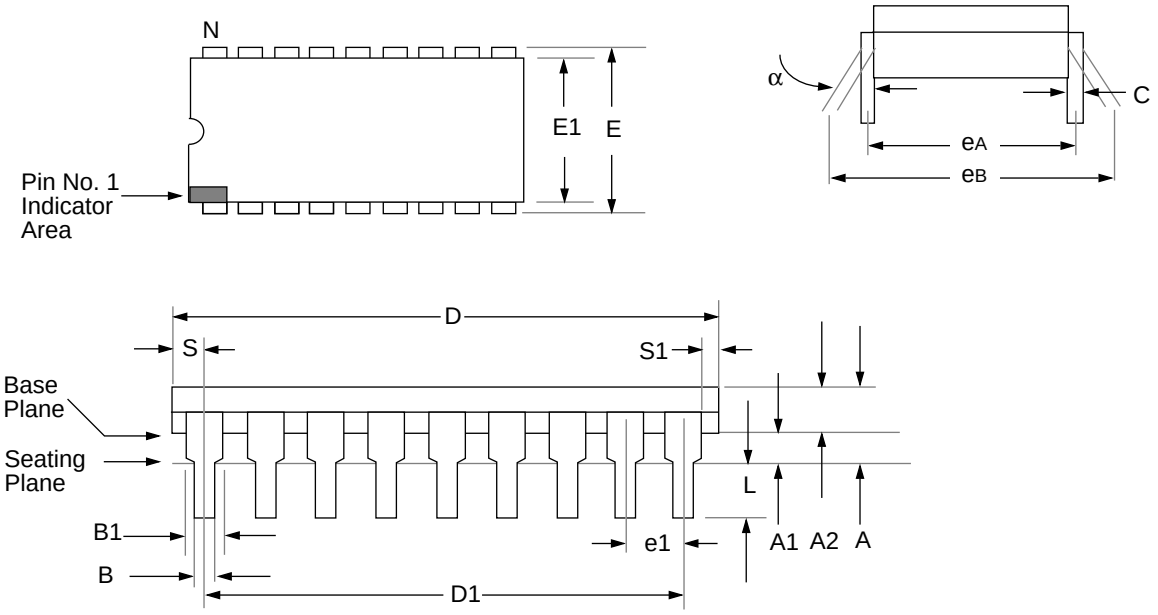


FIGURE 16-22: IOL VS. VOL, VDD = 5V



Data based on matrix samples. See first page of this section for details.

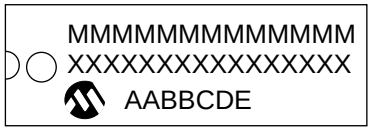
17.2 18-Lead Plastic Dual In-line (300 mil) (P)



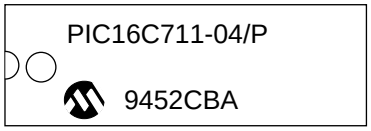
Package Group: Plastic Dual In-Line (PLA)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	4.064		–	0.160	
A1	0.381	–		0.015	–	
A2	3.048	3.810		0.120	0.150	
B	0.355	0.559		0.014	0.022	
B1	1.524	1.524	**Reference**	0.060	0.060	**Reference**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	22.479	23.495		0.885	0.925	
D1	20.320	20.320	**Reference**	0.800	0.800	**Reference**
E	7.620	8.255		0.300	0.325	
E1	6.096	7.112		0.240	0.280	
e1	2.489	2.591	**Typical**	0.098	0.102	**Typical**
eA	7.620	7.620	**Reference**	0.300	0.300	**Reference**
eB	7.874	9.906		0.310	0.390	
L	3.048	3.556		0.120	0.140	
N	18	18		18	18	
S	0.889	–		0.035	–	
S1	0.127	–		0.005	–	

17.5 Package Marking Information

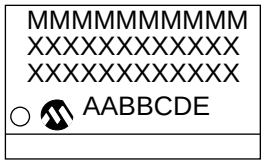
18-Lead PDIP



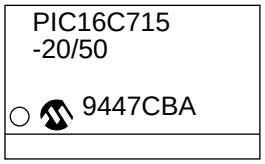
Example



18-Lead SOIC

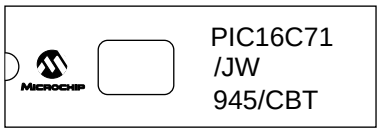


Example



18-Lead CERDIP Windowed

Example



20-Lead SSOP

Example

Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calender year)
	BB	Week code (week of January 1 is week '01')
	C	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D_1	Mask revision number for microcontroller
	E	Assembly code of the plant or country of origin in which part was assembled.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

LIST OF EXAMPLES

LIST OF FIGURES